DEAR COLLEAGUES!

We are pleased to invite you to take part in the 2020 IEEE Third International Conference on Data Stream Mining & Processing (DSMP’2020) which will take place on August 21\textsuperscript{st} up to August 25\textsuperscript{th}, 2020

GOAL

Share the latest methods, technologies and developments in the area of Computational Intelligence, Data Science, Dynamic Data Mining and Video Streams

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CONFERENCE TOPICS

HYBRID SYSTEMS OF COMPUTATIONAL INTELLIGENCE
Information processing systems which combine different approaches of Computational Intelligence, for example, artificial neural networks which are learnt by evolutionary algorithms, neuro-fuzzy systems, wavelet-neuro-fuzzy systems, neuro-neo-fuzzy systems, particle swarm algorithms, evolving systems, deep learning etc.

MACHINE VISION AND PATTERN RECOGNITION
Video Streams that are fed from video cameras in an online mode under environment uncertainty and variability conditions.

DYNAMIC DATA MINING & DATA STREAM MINING
Data Mining problems (classification, clustering, prediction, identification etc.) when information is fed in an online mode in the form of data streams.

BIG DATA & DATA SCIENCE USING INTELLIGENT APPROACHES
Systems of Computational Intelligence (artificial neural networks, fuzzy reasoning systems, evolutionary algorithms) in the tasks of Big Data processing (high-dimensional data) where data are stored in VLDB or fed in an unlimited data stream. Natural Language Processing - machine learning using to get the semantic objects from natural language; the deep learning methods for natural language understanding.

WORKSHOP “ON-LINE DATA PROCESSING”
The selected papers, which will have been presented at this workshop “On-line Data Processing”, will be published in Book series “Communications in Computer and Information Science” publisher “Springer Verlag”. CCIS is indexed in DBLP, Google Scholar, EI-Compendex, Mathematical Reviews, SCImago, Scopus, Conference Proceedings Citation Index (CPCI) which is the part of Clarivate Analytics’ Web of Science. Moreover, this edition is a periodic (it has both ISSN and ISBN numbers).

PANELS
This event is devoted to share resources and ideas with all scientific associations and R&D departments of tech companies & firms.
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DATE & LOCATION
August 21\textsuperscript{st} to 25\textsuperscript{th}, 2020, Lviv, Ukraine

IMPORTANT DATES

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SUBMISSION & TEMPLATES

English is the official language of the DSMP'2020. It shall be used for all printed materials, presentations and discussions. Submitted publication should contain original materials which has not been previously published and is not under review elsewhere.

The size of the conference paper should be from 4 to 6 full A4 pages adjusted according to the IEEE Conference Proceedings Templates.

All the participants WITH CONFERENCE PAPER(S) submissions should make sure they follow next TWO STEPS:

1. Papers should be submitted online via EasyChair system in one of the suggested formats: DOC(DOCX) or PDF (for TEX created ones) Submit Paper.

2. After notification of paper acceptance fill out the Package Registration Form With Paper and attach final paper. You should also attach either a .doc (.docx) file or a .zip file (containing a .tex file and figures) to the form.

All the participants WITHOUT CONFERENCE PAPER should only fill out the Package Registration Form Without Paper.

It is a requirement that at least the one presenting author of every accepted paper must get registered, pay a participation fee and take part in the conference. One author is allowed to submit and present not more than 3 papers.
DSMP’2020 will have a single-round blind peer review process. All submitted papers will be sent to three independent anonymous reviewers. All accepted papers which will be presented at the conference will be submitted to be included to the IEEE Xplore Digital Library as well as other Abstracting and Indexing (A&I) databases (Scopus, Web of Science and etc.).

“No-show” papers won’t be included into the IEEE Xplore Digital Library.

Guidelines for Authors of Papers to be Published in Springer Computer Science Proceedings (Communications in Computer and Information Science (CCIS)) you can download from conference site.

In case you have any questions about workshop, please send your e-mails to ccis.dsmp2020@gmail.com

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